



<b>Title of Change:</b>	Transfer of probe site for SMA3107-TL-E product.	
<b>Proposed Changed Material First Ship Date:</b>	02 May 2019	
<b>Current Material Last Order Date:</b>	NA Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.	
<b>Current Material Last Delivery Date:</b>	NA The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory.	
<b>Product Category:</b>	Active components – Discrete components	
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or < <a href="mailto:Masamichi.Yamamuro@onsemi.com">Masamichi.Yamamuro@onsemi.com</a> >	
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification.	
<b>Sample Availability Date:</b>	NA	
<b>PPAP Availability Date:</b>	NA	
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or < <a href="mailto:Yasuhiro.Igarashi@onsemi.com">Yasuhiro.Igarashi@onsemi.com</a> >.	
<b>Type of Notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change or earlier upon customer approval. ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact < <a href="mailto:PCN.Support@onsemi.com">PCN.Support@onsemi.com</a> >.	
<b>Change Category</b>	<b>Type of Change</b>	
Test Flow	Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor	
<b>Description and Purpose:</b>		
This Product Change Notification announces the transfer of probe test site of SMA3107-TL-E product from ON Semiconductor Shenzhen, China to ON Semiconductor Niigata, Japan, and adding visual inspection process in ON Semiconductor Niigata, Japan.		
	<b>Before Change Description</b>	<b>After Change Description</b>
Probe test	ON Shenzhen	ON Niigata
Visual inspection	—	ON Niigata
<b>Reason / Motivation for Change:</b>	- Quality improvement : Yes Add visual inspection	
<b>Anticipated impact on fit, form, function, reliability, product safety or manufacturability</b>	The device has been qualified and validated based on the same Product Specification. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded.  No anticipated impacts.	



<b>Sites Affected:</b>	ON Semiconductor Sites: ON Shenzhen, China ON Niigata, Japan	External Foundry/Subcon Sites: None
<b>Marking of Parts/ Traceability of Change:</b>	Traceability: date code	
<b>Reliability Data Summary:</b>  Not a change which affects reliability.		
<b>Electrical Characteristic Summary:</b>  Electrical characteristics are not impacted.		
<b>List of Affected Parts:</b>		
<b>Current Part Number</b>	<b>New Part Number</b>	<b>Qualification Vehicle</b>
SMA3107-TL-E	SMA3107-TL-E (no change)	SMA3107-TL-E



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## Appendix A: Changed Products

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Product	Customer Part Number	New Part Number	Qualification Vehicle
SMA3107-TL-E		NA	SMA3107-TL-E